

AMB TYPE

MULTILAYER CHIP BEAD



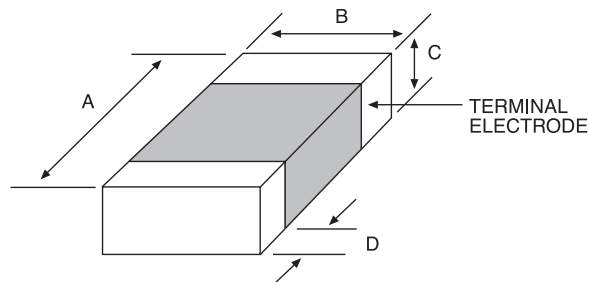
PRODUCT IDENTIFICATION

AMB - 160808 - 0600 N P

1
2
3
4
5

- 1) PRODUCTS SYMBOL
- 2) DIMENSION
- 3) IMPEDANCE
- 4) TYPE
 - N: GENERAL CURRENT
 - H: HIGHT CURRENT
- 5) MATERIAL

SHAPE & DIMENSION



Dimension in mm (inch)

PART NO.	A	B	C	D
AMB160808 (0603)	1.6±0.15 (0.063±0.006)	0.8±0.15 (0.031±0.006)	0.8±0.15 (0.031±0.006)	0.3±0.20 (0.012±0.008)
AMB201209 (0805)	2.0±0.20 (0.079±0.008)	1.2±0.20 (0.047±0.008)	0.9±0.20 (0.035±0.008)	0.5±0.30 (0.020±0.012)
AMB321611 (1206)	3.2±0.20 (0.126±0.008)	1.6±0.20 (0.063±0.008)	1.1±0.20 (0.043±0.008)	0.5±0.30 (0.020±0.012)
AMB321616 (1206)	3.2±0.20 (0.126±0.008)	1.6±0.20 (0.063±0.008)	1.6±0.20 (0.063±0.008)	0.5±0.30 (0.020±0.012)
AMB322513 (1210)	3.2±0.20 (0.126±0.008)	2.5±0.20 (0.098±0.008)	1.3±0.20 (0.051±0.008)	0.5±0.30 (0.020±0.012)
AMB451616 (1806)	4.5±0.20 (0.177±0.008)	1.6±0.20 (0.063±0.008)	1.6±0.20 (0.063±0.008)	0.5±0.30 (0.020±0.012)
AMB453215 (1812)	4.5±0.20 (0.177±0.008)	3.2±0.20 (0.126±0.008)	1.5±0.20 (0.059±0.008)	0.5±0.30 (0.020±0.012)



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STANDARD SPECIFICATION OF MULTILAYER CHIP BEAD

Part Number	Impedance (Ω)	DC Resistance (Ω)	Rated Current (mA)
	at 100 MHz ($\pm 25\%$)	Max.	Max.
AMB160808-0010HD	10	0.03	4000
AMB160808-0025HD	25	0.04	3000
AMB160808-0030NP	30	0.2	200
AMB160808-0030NS	30	0.4	250
AMB160808-0040NP	40	0.3	400
AMB160808-0060NP	60	0.4	200
AMB160808-0080NP	80	0.5	300
AMB160808-0100NP	100	0.4	200
AMB160808-0100NS	100	0.4	200
AMB160808-0120NP	120	0.4	200
AMB160808-0120NS	120	0.4	200
AMB160808-0180NP	180	0.5	200
AMB160808-0220NP	220	0.5	200
AMB160808-0240NP	240	0.5	200
AMB160808-0240NS	240	0.5	200
AMB160808-0300NS	300	0.5	200
AMB160808-0400NS	400	0.5	200
AMB160808-0420NS	420	0.5	200
AMB160808-0450NP	450	0.7	200
AMB160808-0600NP	600	1.0	50
AMB160808-0600ND	600	0.9	150
AMB160808-0600NS	600	0.7	200



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Part Number	Impedance (Ω)	DC Resistance (Ω)	Rated Current (mA)
	at 100 MHz ($\pm 25\%$)	Max.	Max.
AMB-201209-0007NS	7	0.2	300
AMB-201209-0010ND	10	0.2	600
AMB-201209-0010HD	10	0.01	6000
AMB-201209-0011NP	11	0.1	600
AMB-201209-0017NP	17	0.2	600
AMB-201209-0020HD	20	0.03	4000
AMB-201209-0030NS	30	0.4	300
AMB-201209-0030ND	30	0.7	200
AMB-201209-0030HD	30	0.03	4000
AMB-201209-0040HD	40	0.03	4000
AMB-201209-0080NR	80	0.4	400
AMB-201209-0120ND	120	0.6	200
AMB-201209-0120NS	120	0.4	300
AMB-201209-0120NR	120	0.3	300
AMB-201209-0150ND	150	0.6	200
AMB-201209-0220NR	220	0.5	200
AMB-201209-0300ND	300	1.0	200
AMB-201209-0300NS	300	0.5	200
AMB-201209-0400NP	400	0.5	200
AMB-201209-0600ND	600	1.0	200
AMB-201209-0600NS	600	0.5	200
AMB-201209-0600NR	600	0.6	200
AMB-201209-0750NS	750	0.7	200
AMB-201209-1000NS	1000	0.7	200
AMB201209-1000NR	1000	1.0	100
AMB-201209-1200NR	1200	1.0	100
AMB-201209-1500NR	1500	1.0	100

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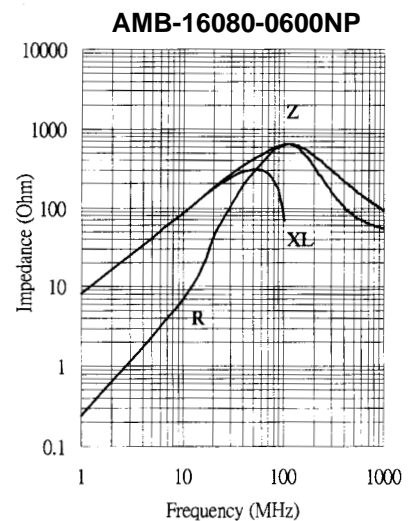
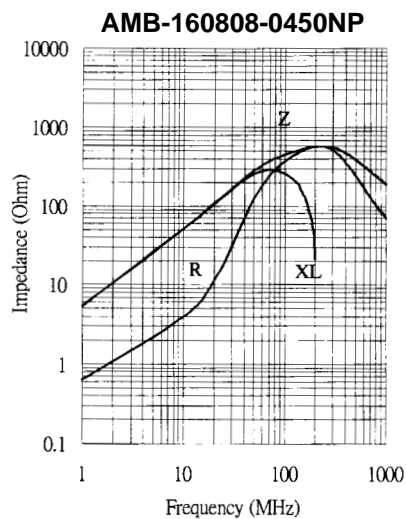
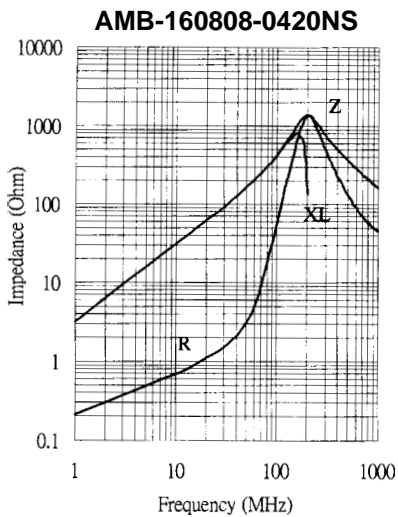
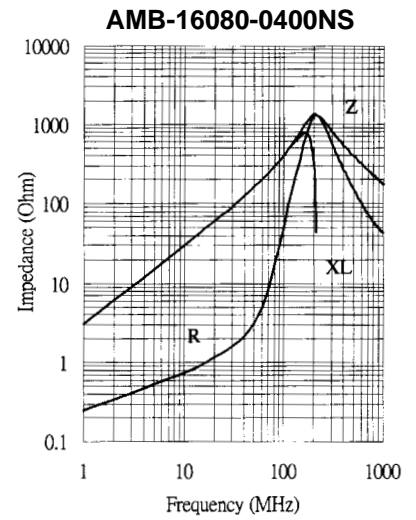
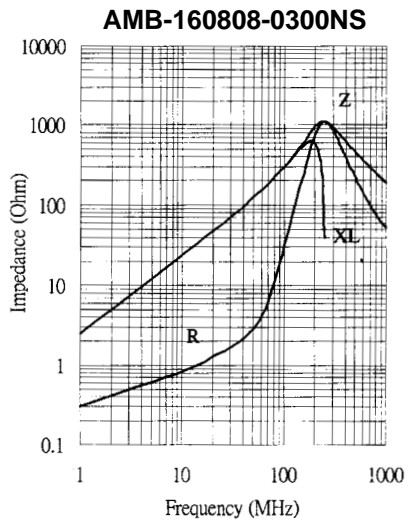
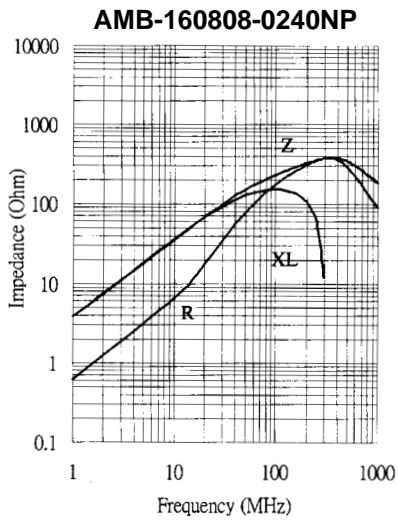
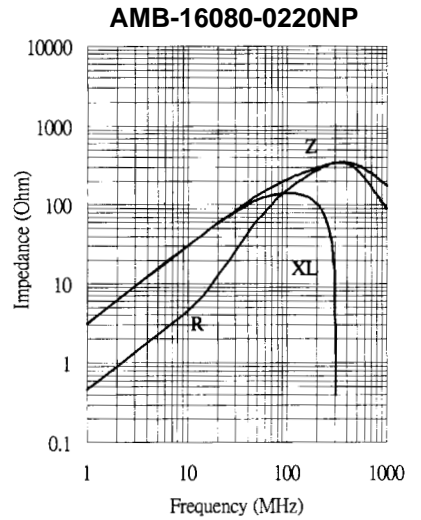
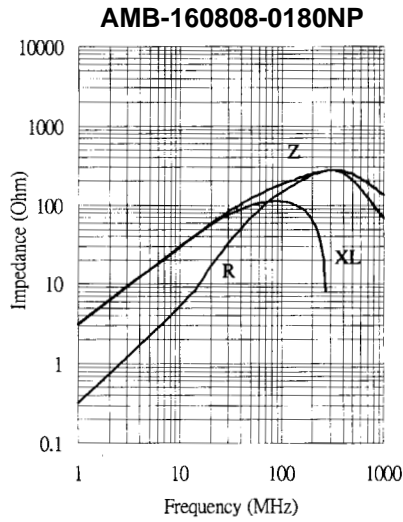
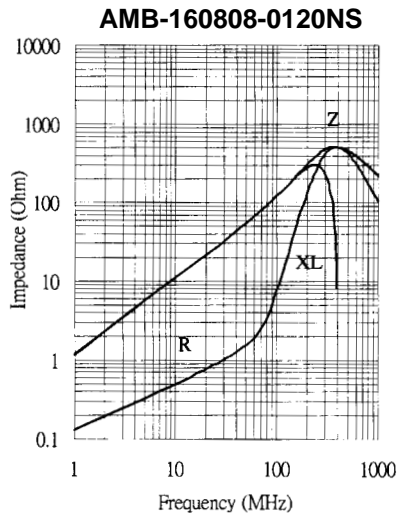
STANDARD SPECIFICATION OF MULTILAYER CHIP BEAD

Part Number	Impedance (Ω)	DC Resistance (Ω)	Rated Current (mA)
	at 100 MHz ($\pm 25\%$)	Max.	Max.
AMB-321611-0019NS	19	0.2	500
AMB-321611-0026ND	26	0.2	500
AMB-321611-0030HD	30	0.03	4000
AMB-321611-0031NP	31	0.2	500
AMB-321611-0050HD	50	0.03	4000
AMB-321616-0050NP	50	0.5	200
AMB-321611-0070NP	70	0.5	200
AMB-321616-0070ND	70	0.5	200
AMB-321611-0080HD	80	0.03	4000
AMB-321611-0090NP	90	0.1	500
AMB-321611-0120NR	120	0.4	500
AMB-321611-0150NR	150	0.4	100
AMB-321611-0220NR	220	0.5	500
AMB-321611-0400NR	400	0.6	100
AMB-321611-0500ND	500	0.5	100
AMB-321611-0600NP	600	0.5	100
AMB-321611-0600ND	600	0.5	200
AMB-321611-1200NP	1200 (at 50 MHz)	0.1	100
AMB-321611-2000NP	2000 (at 30 MHz)	2.1	100
AMB-321611-2000ND	2000 (at 30 MHz)	2.1	100
AMB-322513-0031NS	31	0.3	400
AMB-322513-0052ND	52	0.3	500
AMB-322513-0060NP	60	0.3	200
AMB-451616-0031NS	31	0.3	500
AMB-451616-0050HD	50	0.03	4000
AMB-451616-0052ND	52	0.7	300
AMB-451616-0060NP	60	0.7	300
AMB-451616-0060HD	60	0.03	4000
AMB-451616-0075HD	75	0.03	4000
AMB-451616-0080ND	80	0.7	200
AMB-451616-0080HD	80	0.03	4000
AMB-451616-0125NP	125	0.7	200
AMB-451616-0150NP	150	0.7	200
AMB-453215-0070NS	70	0.4	300
AMB-453215-0120ND	120	0.4	300
AMB-453215-0125NP	125	0.4	300
AMB-453215-0125HP	125	0.04	3000

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TYPICAL ELECTRICAL CHARACTERISTIC CURVES

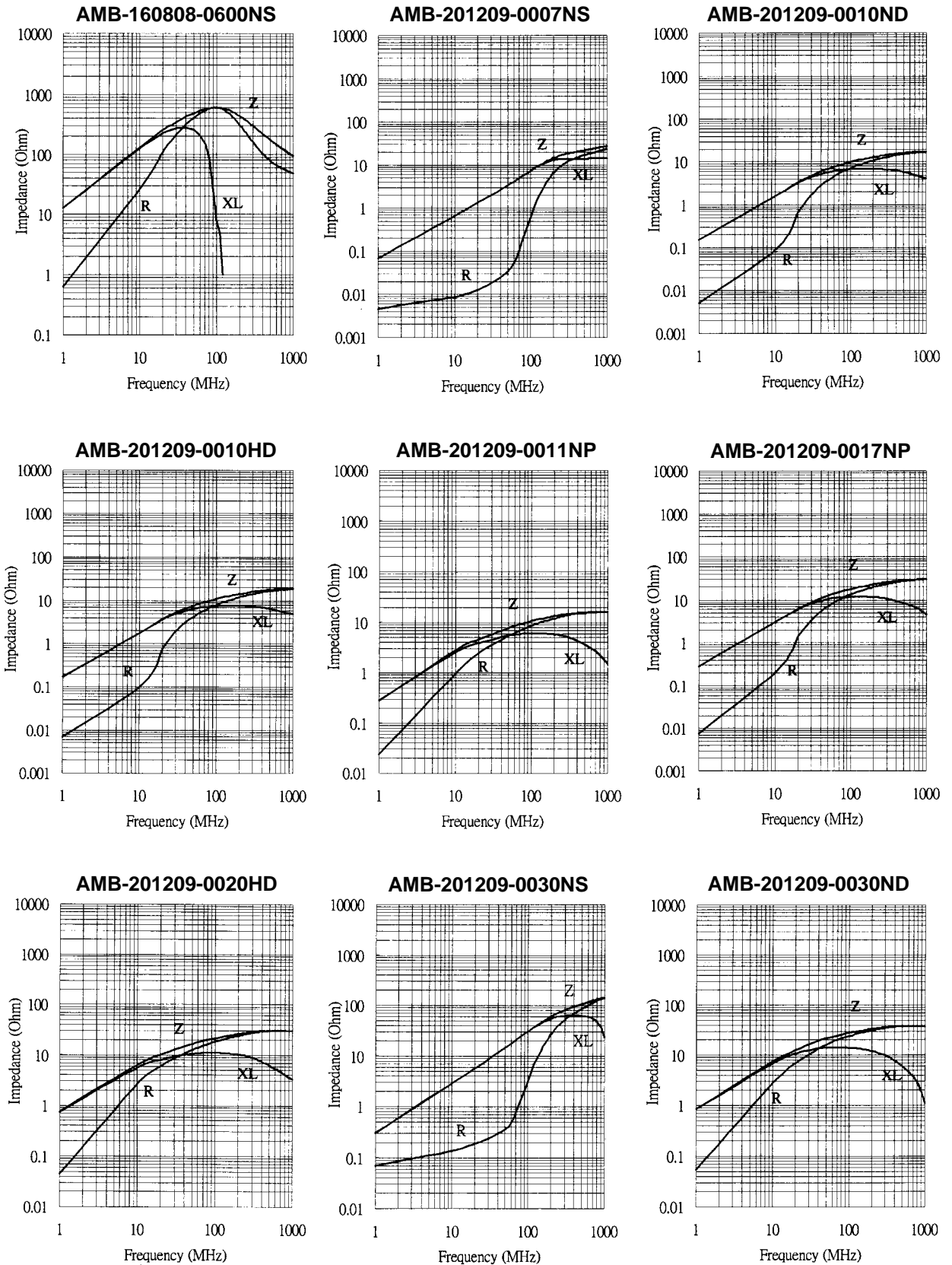
TEST INSTRUMENT: HP - 4291A



AMB TYPE MULTILAYER CHIP BEAD

TYPICAL ELECTRICAL CHARACTERISTIC CURVES

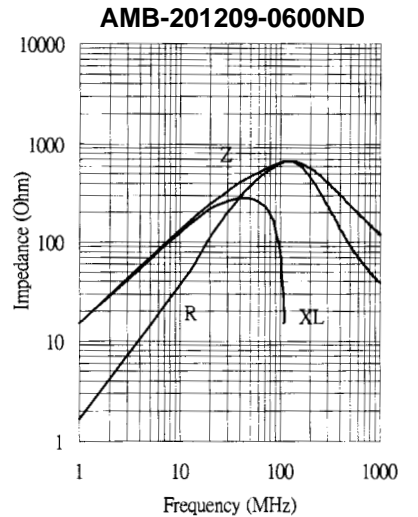
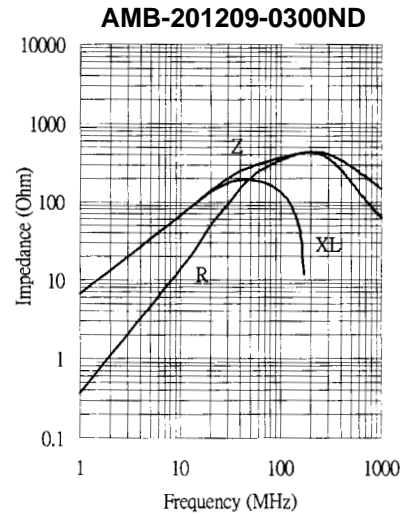
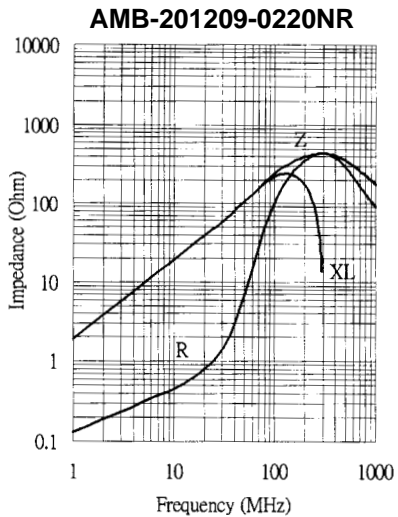
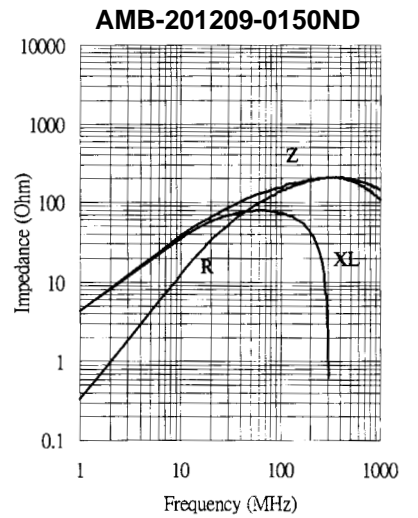
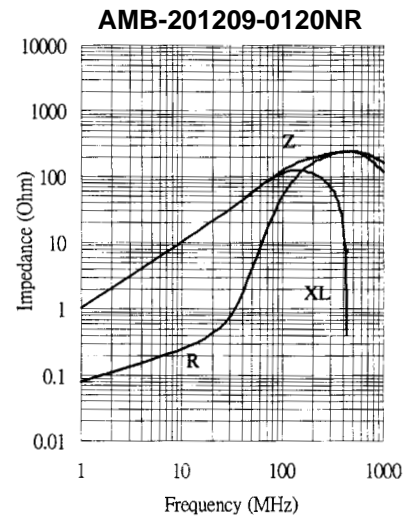
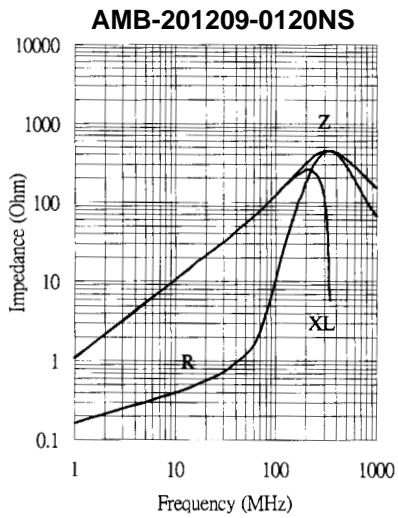
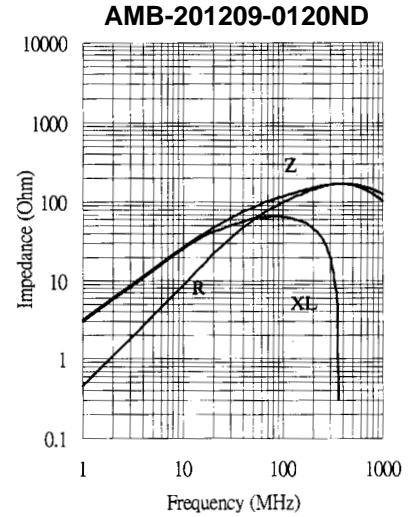
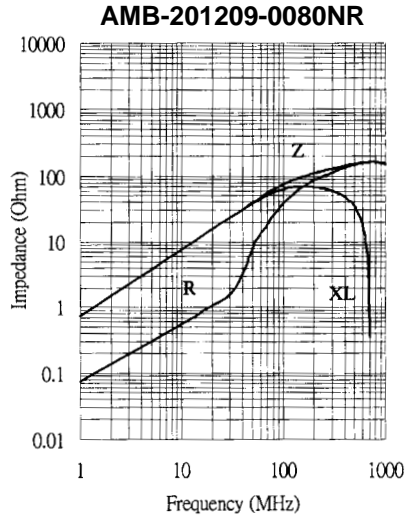
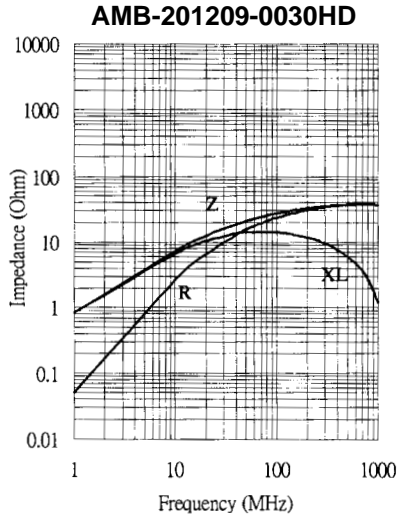
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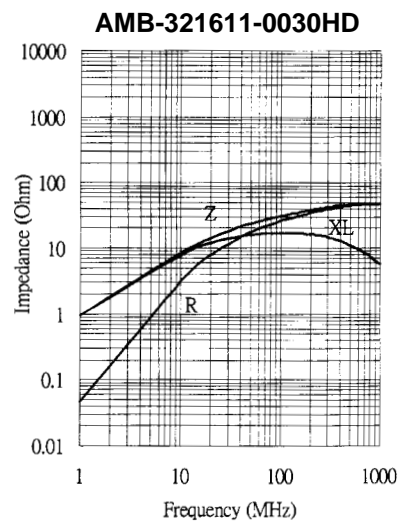
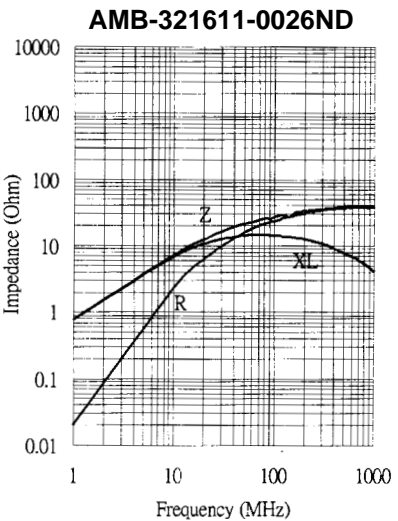
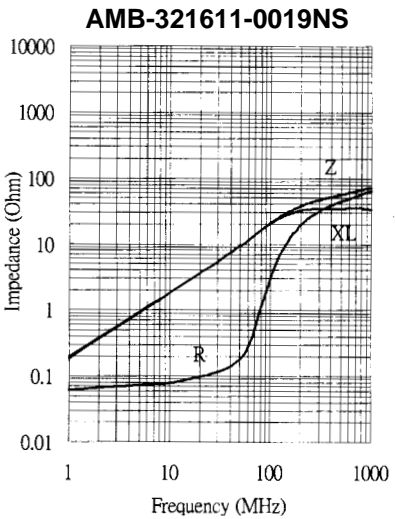
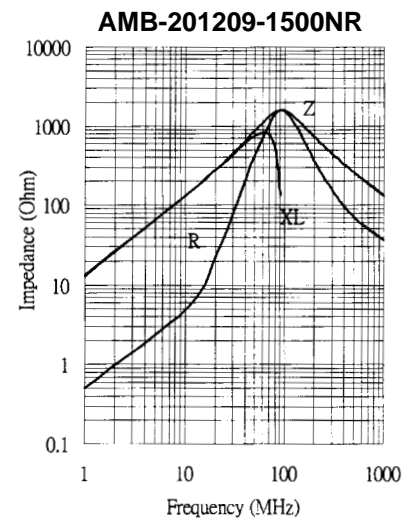
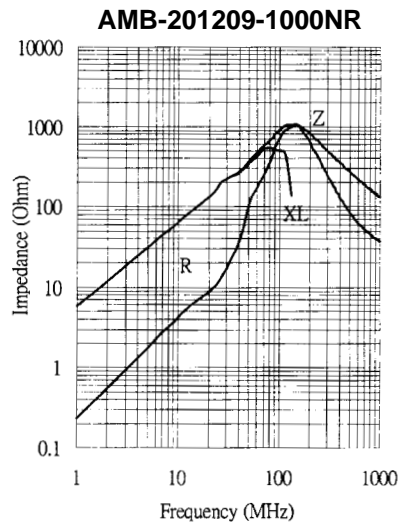
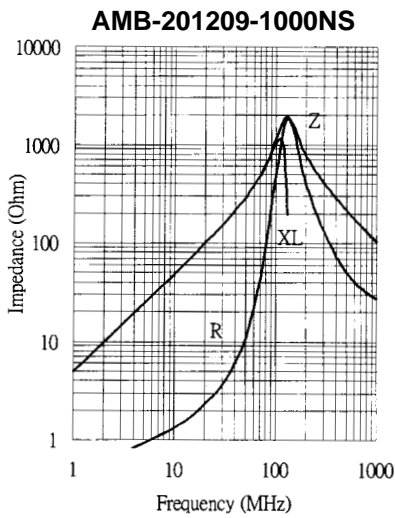
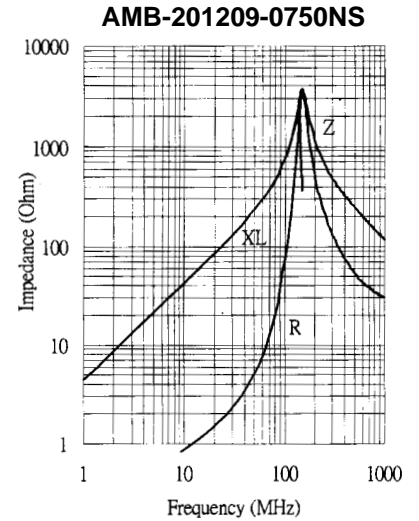
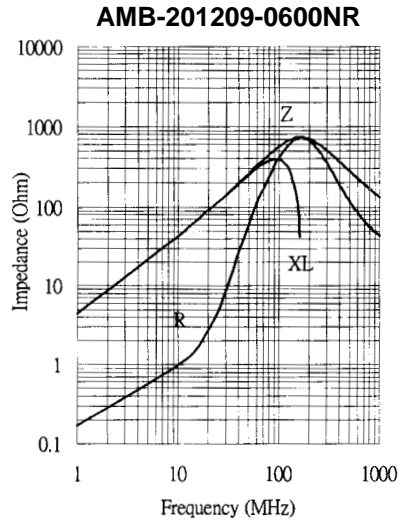
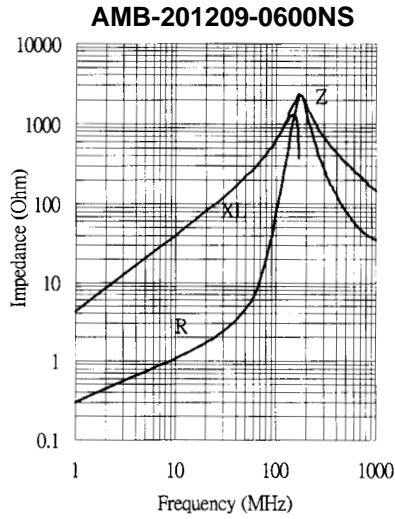




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TYPICAL ELECTRICAL CHARACTERISTIC CURVES

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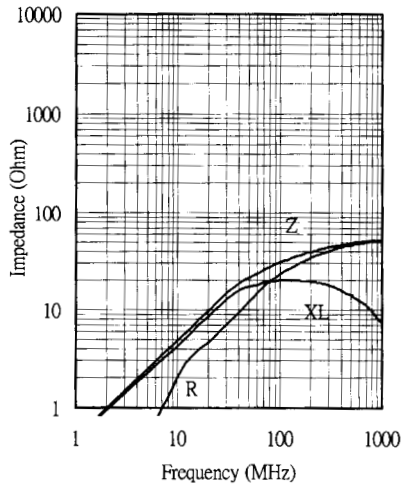


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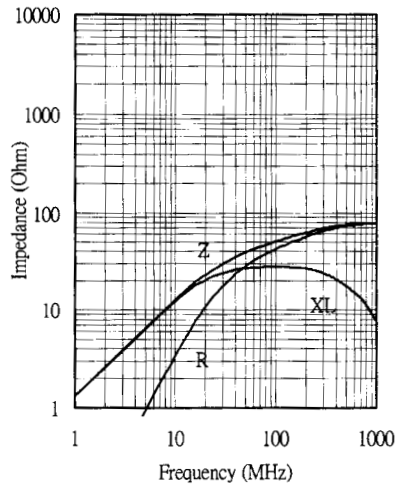
TYPICAL ELECTRICAL CHARACTERISTIC CURVES

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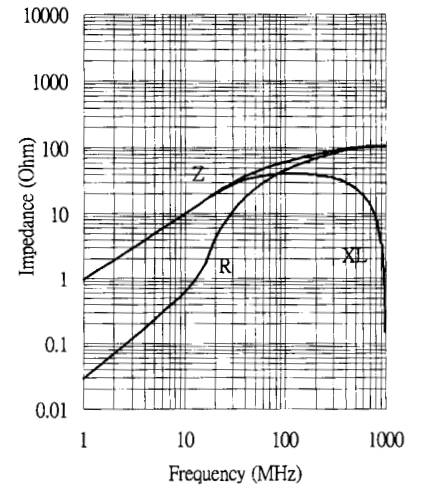
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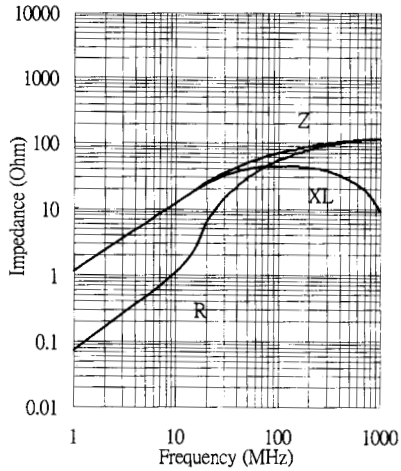
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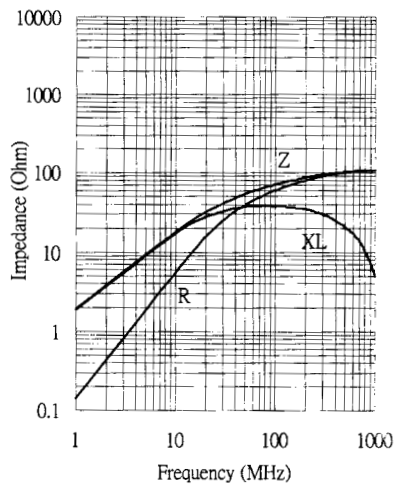
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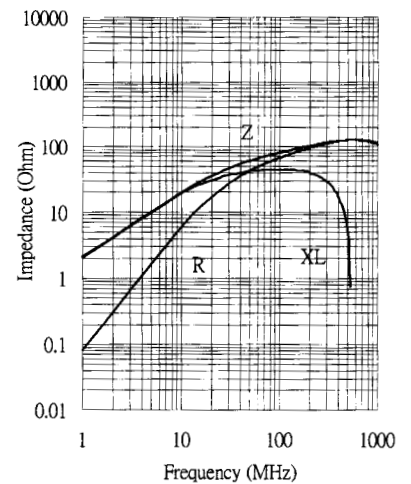
AMB-321611-0070NP



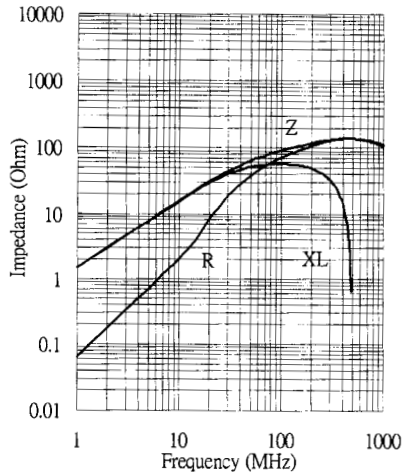
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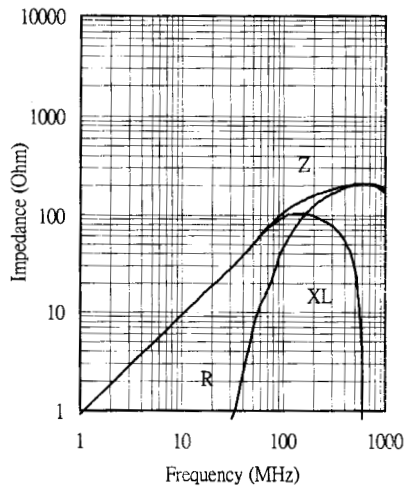
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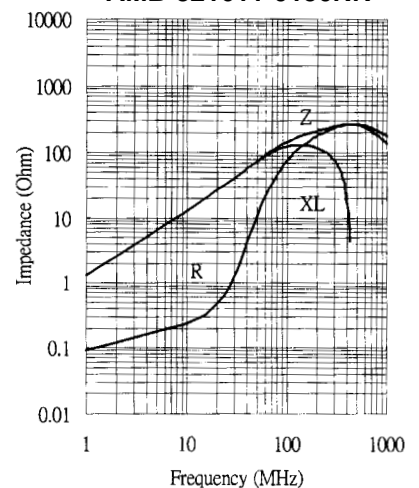
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AMB-321611-0120NR



AMB-321611-0150NR

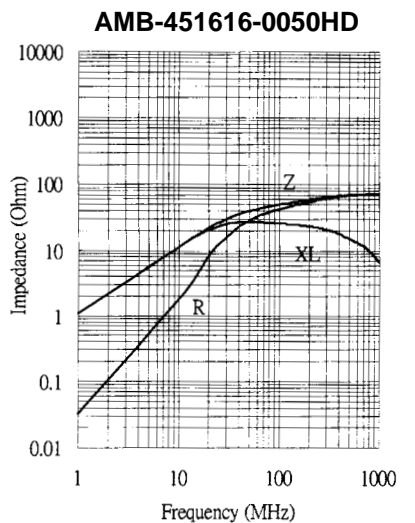
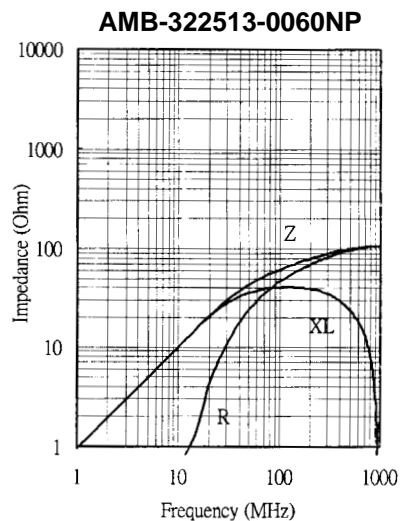
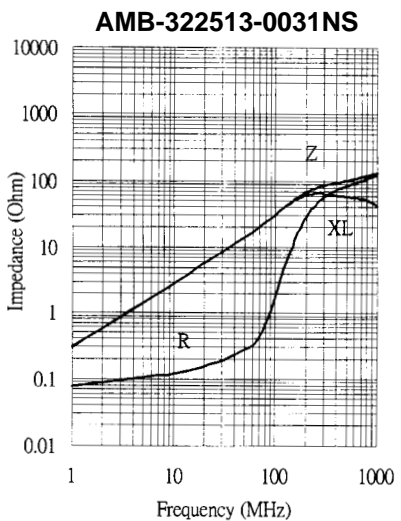
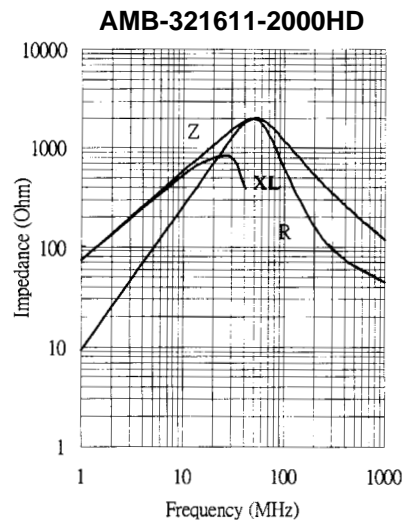
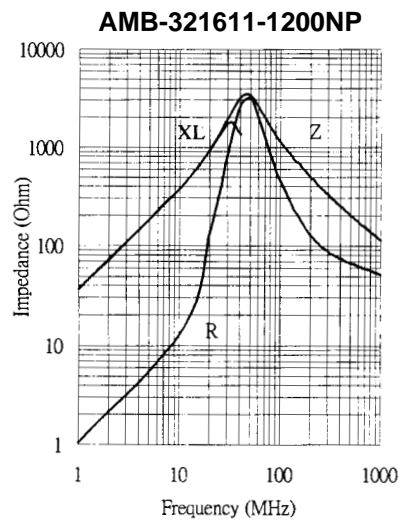
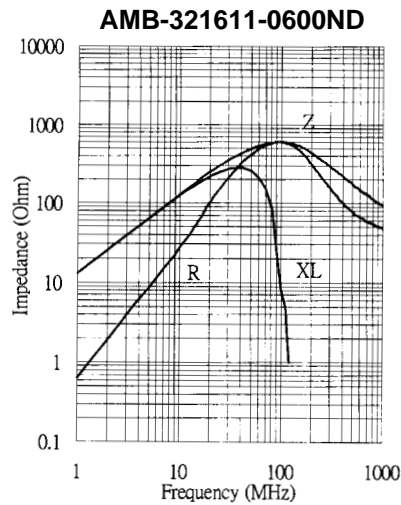
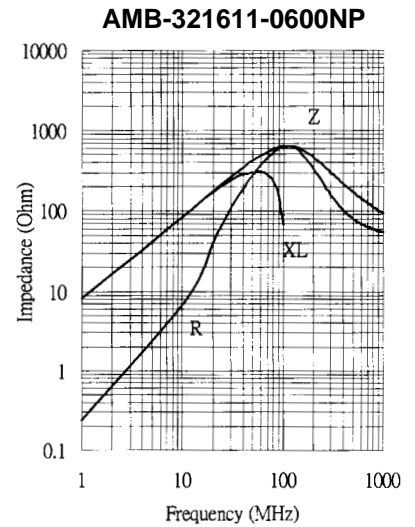
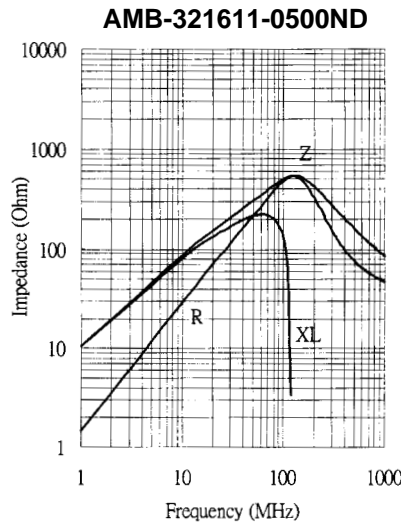
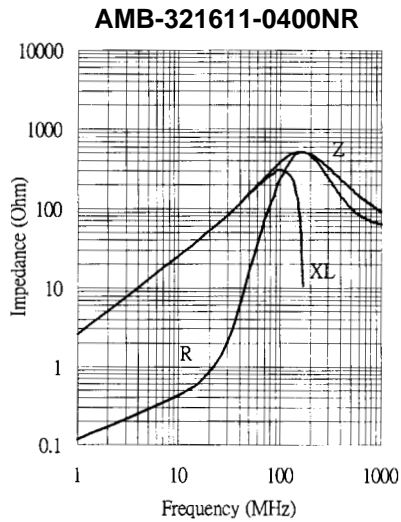




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TYPICAL ELECTRICAL CHARACTERISTIC CURVES

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RELIABILITY TEST

MECHANICAL PERFORMANCE TEST

ITEM	SPECIFICATION	TEST CONDITION		
SOLDERABILITY	MORE THAN 90% OF THE TERMINAL	SOLDER: H63A (EUTECTIC SOLDER)		
	ELECTRODE SHALL BE COVERED WITH FRESH SOLDER.	SOLDER TEMPERATURE: 230°C±5°C FLUX: ROSIN DIP TIME: 3±1 SECONDS		
SOLDERING HEAT RESISTANCE	THE CHIP SHALL NOT CRACK. MORE THAN 75% OF THE TERMINAL	SOLDER: H63A(EUTECTIC SOLDER)		
	ELECTRODE SHALL BE COVERED WITH SOLDER.	SOLDER TEMPERATURE: 260°C±5°C FLUX: ROSIN DIP TIME: 10±1 SECONDS		
TERMINAL STRENGTH	THE TERMINAL ELECTRODE SHALL NOT BREAK OFF NOR THE FERRITE DAMAGE.	TYPE	KGf	TIME (SEC)
		AMB-160808	0.6	30±5
		AMB-201209	0.6	30±5
		AMB-321611	1.0	30±5
		AMB-321616	1.0	30±5
		AMB-322513	1.0	30±5
		AMB-451616	1.0	30±5
		AMB-453215	1.5	30±5
BENDING STRENGTH	THE FERRITE SHALL NOT BE DAMAGED BY FORCES APPLIED ON THE RIGHT.	TYPE	A(MM)	KGf
		AMB-160808	1.0	0.6
		AMB-201209	1.4	1.0
		AMB-321611	2.0	2.0
		AMB-321616	2.0	2.5
		AMB-322513	2.0	2.5
		AMB-451616	2.5	2.5
		AMB-453215	2.7	2.5

CLIMATIC TEST

THERMAL SHOCK (TEMPERATURE CYCLE)		TEMPERATURE: -55°C, +125°C FOR 30 MINUTES EACH, 50 CYCLES
HUMIDITY RESISTANCE	IMPEDANCE SHALL BE WITHIN ±20% OF THE INITIAL VALUE.	TEMPERATURE: +60°C HUMIDITY: 90 % RH APPLIED CURRENT: RATED CURRENT TIME: 1000±12 HOURS
HIGH TEMPERATURE RESISTANCE		TEMPERATURE: +80°C APPLIED CURRENT: RATED CURRENT TIME: 1000±12 HOURS

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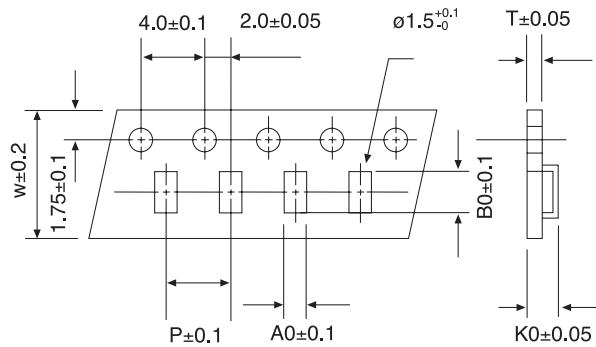
STANDARD PACKAGING

TAPE DIMENSION

Dimension in mm

TYPE	A0	B0	K0	W	P	T
AMB-453215	3.6	4.9	1.9	12	8	0.25
AMB-451616	1.9	4.9	2.0	12	4	0.25
AMB-322513	2.9	3.6	1.7	8	4	0.25
AMB-321616	1.9	3.5	2.0	8	4	0.25
AMB-321611	1.9	3.5	1.5	8	4	0.25
AMB-201209	1.5	2.3	1.3	8	4	0.25
AMB-160808	1.1	1.9	1.1	8	4	0.25

CARRIER TAPE MATERIAL:
POLYSTYRENE



REEL DIMENSION

Dimension in mm

TYPE	Q'TY	A	B	C	G	N	T
AMB-453215	1000 pcs	178	21.0	13.0	12.4	55	16.4
AMB-451616	2000 pcs	178	21.0	13.0	12.4	55	16.4
AMB-322513	2500 pcs	178	21.0	13.0	8.4	55	12.4
AMB-321616	2500 pcs	178	21.0	13.0	8.4	55	12.4
AMB-321611	3000 pcs	178	21.0	13.0	8.4	55	12.4
AMB-201209	4000 pcs	178	21.0	13.0	8.4	55	12.4
AMB-160808	4000 pcs	178	21.0	13.0	8.4	55	12.4

